

**Compound copper-aluminium wire and its production process**

**Patent number:** CN1230754  
**Publication date:** 1999-10-06  
**Inventor:** PENG XINGKUI (CN)  
**Applicant:** PENG XINGKUI (CN)  
**Classification:**  
- **international:** H01B5/02; H01B5/00; H01B13/00  
- **european:**  
**Application number:** CN19980112410 19980326  
**Priority number(s):** CN19980112410 19980326

[Report a data error here](#)

**Abstract of CN1230754**

The compound wire consists of coated copper layer and aluminum core, which are metallurgically combined firmly through solid phase combination process without formed harmful fragile intermediate compound. The compound wire of the present invention has high conductivity, low specific weight, low contact resistance and cost greatly lower than that of copper wire. It may be used as a substitute of pure copper wire and pure aluminum wire widely in power and electronic industry.

---

Data supplied from the esp@cenet database - Worldwide